APPLICABLE STANDARD				
RATING	OPERATING TEMPERATURE RANGE	-55 °C TO 85 °C (1)	STORAGE TEMPERATURE RANGE	-10 °C TO 60 °C (2)
	VOLTAGE	50 V AC	STORAGE HUMIDITY RANGE	RELATIVE HUMIDITY 85% max (NOT DEWED)
	CURRENT	0.5 A	OPERATING HUMIDITY RANGE	

SPECIFICATIONS

ITEM	TEST METHOD	REQUIREMENTS	QT	AT
CONSTRUCTION				
GENERAL EXAMINATION	VISUALLY AND BY MEASURING INSTRUMENT.	ACCORDING TO DRAWING.	×	×
MARKING	CONFIRMED VISUALLY.		×	×
ELECTRIC CHARACTERISTICS				
CONTACT RESISTANCE	100 mA(DC OR 1000Hz)	70 mΩ MAX.	×	—
INSULATION RESISTANCE	100 V DC.	100 MΩ MIN.	×	—
VOLTAGE PROOF	150 V AC FOR 1 min.	NO FLASHOVER OR BREAKDOWN.	×	×
MECHANICAL CHARACTERISTICS				
INSERTION AND WITHDRAWAL FORCES	MEASURED BY APPLICABLE CONNECTOR.	INSERTION FORCE: 84 N MAX. WITHDRAWAL FORCE: 10.3 N MIN.	×	—
MECHANICAL OPERATION	50 TIMES INSERTIONS AND EXTRACTIONS.	① CONTACT RESISTANCE: △1 VARIATION FROM INITIAL VALUE 20 mΩ OR LESS. ② NO DAMAGE, CRACK AND LOOSENESS OF PARTS.	×	—
VIBRATION	FREQUENCY 10 TO 55 TO 10Hz, APPROX 5min SINGLE AMPLITUDE : 0.75 mm, 10 CYCLES FOR 3 DIRECTIONS.	① NO ELECTRICAL DISCONTINUITY OF 1 μs. ② NO DAMAGE, CRACK AND LOOSENESS OF PARTS.	×	—
SHOCK	490 m/s², DURATION OF PULSE 11 ms AT 3 TIMES FOR 3 DIRECTIONS.		×	—
ENVIRONMENTAL CHARACTERISTICS				
DAMP HEAT (STEADY STATE)	EXPOSED AT 40±2 °C, 90 ～ 95 %, 96 h.	① CONTACT RESISTANCE: △1 VARIATION FROM INITIAL VALUE 20 mΩ OR LESS. ② INSULATION RESISTANCE :100 MΩ MIN. ③ NO DAMAGE, CRACK AND LOOSENESS OF PARTS.	×	—
RAPID CHANGE OF TEMPERATURE	TEMPERATURE -55 → +85 °C TIME 30 → 30 min. UNDER 5 CYCLES. (RELOCATION TIME TO CHAMBER:WITHIN 2～3 MIN)		×	—
COLD	EXPOSED AT -55℃, 96 h	① CONTACT RESISTANCE: △1 VARIATION FROM INITIAL VALUE 20 mΩ OR LESS. ② NO DAMAGE, CRACK AND LOOSENESS OF PARTS.	×	—
DRY HEAT	EXPOSED AT 85℃, 96 h		×	—
SULFUR DIOXIDE	EXPOSED AT 25±2℃, 75±5%RH, 25 PPM FOR 96 h. (TEST STANDARD: JIS C 60068)	① NO DEFECT SUCH AS CORROSION WHICH IMPAIRS THE FUNCTION OF CONNECTOR. ② CONTACT RESISTANCE: △1 VARIATION FROM INITIAL VALUE 20 mΩ OR LESS.	×	—
RESISTANCE TO SOLDERING HEAT	1)REFLOW SOLDERING : PEAK TMP : 260℃MAX REFLOW TMP: 220℃MIN FOR 60sec 2) SOLDERING IRONS : 360℃ MAX. FOR 5 sec.	NO DEFORMATION OF CASE OF EXCESSIVE LOOSENESS OF THE TERMINAL.	×	—
SOLDERABILITY	SOLDERED AT SOLDER TEMPERATURE 240±3℃ FOR IMMERSION DURATION, 3 sec.	A NEW UNIFORM COATING OF SOLDER SHALL COVER A MINIMUM OF 95 % OF THE SURFACE BEING IMMERSED.	×	—

	COUNT	DESCRIPTION OF REVISIONS	DESIGNED	CHECKED	DATE
△1	4	DIS-F-005857	KT.DOI	KI.HIROKAWA	11.11.24

REMARKS (1) INCLUDE TEMPERATURE RISE CAUSED BY CURRENT-CARRYING.
(2) "STORAGE" MEANS A LONG-TERM STORAGE STATE FOR THE UNUSED PRODUCT BEFORE ASSEMBLY TO PCB.

Unless otherwise specified, refer to JIS-C-5402.

APPROVED	HS.OKAWA	11.08.22
CHECKED	KI.HIROKAWA	11.08.12
DESIGNED	KT.DOI	11.08.12
DRAWN	KT.DOI	11.08.12

Note QT:Qualification Test AT:Assurance Test X:Applicable Test

DRAWING NO. ELC4-336323-00

HRS	SPECIFICATION SHEET	PART NO.	FX20-120P-0.5SV15	
	HIROSE ELECTRIC CO., LTD.	CODE NO.	CL570-1005-1-00 △1	1/1

FORM HD0011-2-1